L Number	Hits	Search Text	DB	Time stamp
1	0	@ad<=20021101 and 'schottky' same 'silicide' and 'TiW' with 'platimun' and 'field oxide'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:18
2	0	@ad<=20021101 and 'schottky' same 'silicide' and 'TiW' with 'platimun'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:18
3	0	@ad<=20021101 and 'schottky' same 'silicide' and 'TiW' with 'platinum' and 'field oxide'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:18
4	13	@ad<=20021101 and 'silicide' with 'TiW' with 'platinum' and 'field oxide'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:36
5	2	"20030132522"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:35
6	1	@ad<=20021101 and 'silicide' with 'TiW' with 'platinum' same 'interconnect'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:36
7	0	@ad<=20020111 and 'metallization' and 'silicide' with 'Titanium' adj1 'tungsten' with 'noble metal'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:40
8	11	@ad<=20020111 and 'metallization' and ('Titanium-tungsten' or 'TiW') with 'noble metal'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:41
10	9	@ad<=20021101 and MEMS and silicide and TiW and platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:53
11	40	@ad<=20021101 and silicide with TiW with platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:54
151	203	(257/449).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:21
156	59	(257/451).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:22
157	117	(257/452).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:22
158	293	@ad<=20020111 and (257/453-457).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:00

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159	2	("4063964").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:00
160	19	'analog device' and 'TIW' and 'platinum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:27
161	0	alie-a-susan.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:36
162	0	alie-susan.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:36
163	0	alie-susan.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:36
164	3	nunan-kieran.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:36
-	17647	@ad<=20021101 and MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:46
-	132738	@ad<=20021101 and platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:08
-	99	@ad<=20021101 and titanium adj1 tungsten and 'platinum silicide' and interconnection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 15:13
-	1273	@ad<=20021101 and MEMS and interconnection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:07
-	281	@ad<=20021101 and titanium adj1 tungsten and 'platinum silicide'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 14:12
-	349	@ad<=20021101 and 'schottky' and titanium adj1 tungsten	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 10:05
-	16	@ad<=20021101 and 'schottky barrier' and MEMS	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 14:56
-	9	@ad<=20021101 and 'schottky barier'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 14:58

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-	22495	@ad<=20021101 and 'schottky'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 15:00
-	628	(@ad<=20021101 and 'schottky') and platinum adj silicide	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 15:01
-	117	((@ad<=20021101 and 'schottky') and platinum adj silicide) and titanium adj tungsten	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:16
-	117	(((@ad<=20021101 and 'schottky') and platinum adj silicide) and titanium adj tungsten) and platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 15:53
-	830	@ad<=20020111 and titanium adj tungsten with platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 15:50
-	13	(((@ad<=20021101 and 'schottky') and platinum adj silicide) and titanium adj tungsten) and platinum with conductive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 15:54
-	963	(@ad<=20021101 and MEMS) and platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:09
-	0	(@ad<=20021101 and MEMS) and platinum adj metallization	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:10
-	47	'platinum metallization'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:10
-	1	"5187547".PN.	USPAT; US-PGPUB	2002/09/11 16:28
-	16	@ad<=20021101 and wachtmann.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:51
-	0	kneedler.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:51
-	88	limb.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:52
-	0	limb-scott.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:53
-	81	nunan.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 16:53

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-	1	nunan-k.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 17:11
-	1702	analog adj1 devices.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 17:14
-	130	(analog adj1 devices.as.) and "257"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/11 17:15
-	70	((257/255).CCLS.) and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:53
-	2742	((257/485-486) or (257/471) or (257/369) or (257/383-384)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:53
-	39	((257/455).CCLS.) and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 10:57
-	103	((257/485).CCLS.) and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/12 08:04
-	46	(((257/485-486) or (257/471) or (257/369) or (257/383-384)).CCLS.) and titanium adj tungsten and platinum and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 09:43
-	0	(((257/485-486) or (257/471) or (257/369) or (257/383-384)).CCLS.) and titanium adj tungsten and 'platinum wire' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/12 08:36
-	45	'platinum wire' and @ad<=20020111 and 'silicide'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/12 08:36
-	55	@ad<=20021101 and MEMS and titanium adj tungsten	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/12 08:59
-	19	@ad<=20021101 and MEMS and titanium adj tungsten and platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 09:59
-	1	"6063442".PN.	USPAT	2002/09/12 09:20
-	1	"5837562".PN.	USPAT	2002/09/12 09:20
-	1	"5731587".PN.	USPAT	2002/09/12 09:21
-	2	("3798145").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/12 11:47

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-	2	("5672898").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/09/12 11:47
-	71	((257/255).CCLS.) and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 09:22
-	69	(257/454-456).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:54
-	46	(((257/485-486) or (257/471) or (257/369) or (257/383-384)).CCLS.) and titanium adj tungsten and platinum and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 09:44
-	198	'silicide' with 'titanium' adj 'tungsten' with platinum and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 10:16
-	20	'silicide' with 'Ti' adj1 'W' with 'platinum' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 09:46
-	341	(438/570).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:56
-	27	(438/575).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:56
-	164	(438/580-582).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:54
-	196	(438/580-583).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:55
-	28	@ad<=20021101 and MEMS and titanium adj tungsten and platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 09:29
-	115	@ad<=20021101 and 'schottky' and 'platinum electrode'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 10:05
-	0	'silicide' with 'titanium' adj 'tungsten' with 'platinum electrode' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:13
-	9	'silicide' with 'titanium' adj 'tungsten' and 'platinum electrode' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 10:17

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-	0	'schottky' with 'titanium' adj 'tungsten' and 'platinum electrode' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/31 10:18
-	4	'schottky' and 'titanium' adj 'tungsten' and 'platinum electrode' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 09:31
-	3	@ad<=20021101 and 'MEMS' and 'silicide' same 'titanium tungsten' same 'platinum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:19
-	368	'silicide' same 'titanium tungsten' same 'platinum' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 08:46
-	1	'silicide' same 'titanium tungsten' same 'platinum' and @ad<=20020111 and 'MEMS'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:58
-	3	@ad<=20021101 and 'MEMS' and 'silicide' and 'titanium tungsten' and 'platinum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 10:13
-	1	"3665241".PN.	USPAT	2003/04/20 07:23
-	0	@ad<=20020111 and 'microelectromechanical system' and 'silicide' and 'titanium-tungsten' and 'platinum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:48
-	1509	@ad<=20020111 and 'microelectromechanical system'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:56
-	0	(@ad<=20020111 and 'microelectromechanical system') and 'silicide' with 'TiW' with 'platinum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:57
-	0	(@ad<=20020111 and 'microelectromechanical system') and 'silicide' and 'TiW' and 'platinum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:57
-	0	(@ad<=20020111 and 'microelectromechanical system') and 'silicide' same 'titanium-tungsten' same 'platinum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:58
-	1	'silicide' same 'titanium tungsten' same 'platinum' and (@ad<=20020111 and 'microelectromechanical system')	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 07:59
-	2	cohn-michael.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 08:00
-	7	cohn.in. and 'MEMS'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 08:00

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-	1	('silicide' same 'titanium tungsten' same 'platinum' and @ad<=20020111) and 'MEMS'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:05
-	1	@ad<=20020111 and MEMS and silicide and titanium adj1 tungsten and platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:57
-	4	'schottky' and 'titanium' adj 'tungsten' and 'platinum electrode' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 09:31
-	1436	(257/99).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:56
-	1375	(257/532).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 13:17
-	1	'silicide' same 'TiW' same 'platinum' and @ad<=20020111 and 'MEMS'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:06
-	2	'silicide' same 'TiW' same 'platinum electrode' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:10
-	87	'silicide' same 'TiW' same 'platinum' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:10
-	16	'silicide' same 'barrier' same 'platinum electrode' and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:11
-	0	@ad<=20020111 and PtSi with TiW with 'noble metal'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:59
-	0	@ad<=20020111 and 'silicide\TiW\Pt'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:59
-	0	@ad<=20020111 and silicidei adj2 TiW adj2 'noble metal'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 11:36
-	0	@ad<=20020111 and silicidei adj2 TiW adj2 platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 10:00
-	0	@ad<=20020111 and silicide adj2 TiW adj2 platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 09:59

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-	39	@ad<=20020111 and silicide with TiW with platinum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 10:02
-	0	@ad<=20020111 and silicide with TiW with 'noble metal'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 10:00
-	1	@ad<=20020111 and silicide with TiW same 'Platinum layer'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 10:01
-	9	@ad<=20021101 and 'MEMS' and 'silicide' and 'TiW' and 'platinum'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 10:32
-	37	@ad<=20021101 and 'TiW' with 'platinum' and 'interconnection'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:20
-	22	@ad<=20021101 and 'TiW' with 'platinum' and 'silicide' and 'interconnection'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 10:40
-	103	@ad<=20021101 and 'diffusion barrier' with 'TaN' with 'TiN' with 'TiW'	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:21
-	3119	((257/485-486) or (257/471) or (257/369) or (257/383-384)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:56
-	75	((257/255).CCLS.) and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:56
-	74	(257/454-456).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:57
-	189	(438/580-582).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:56
-	231	(438/580-583).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:57
-	355	(438/570).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:57
-	34	(438/575).CCLS. and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:57

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-	1516	(257/99).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 11:59
-	1433	(257/532).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 12:00
-	3007	(((257/485-486) or (257/471) or (257/369) or (257/383-384)).CCLS.) and @ad<=20021101	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 12:03
-	1023	(257/751).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 13:19
-	683	(257/754).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 13:19
-	355	(257/768).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 13:20
-	462	(257/769-770).CCLS. and @ad<=20020111	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/12 13:20

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